

TFA



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eskridge, Mark H.

Attorney Docket No. H0005288  
H000-1-1151

Serial No. 10/804,609

Group Art Unit: 2814

Filing Date: March 18, 2004

Examiner: NGUYEN, Dilinh

Title: FLIP CHIP BONDED MICRO-ELECTROMECHANICAL SYSTEM (MEMS)  
DEVICE

## AMENDMENT TRANSMITTAL LETTER

TO THE COMMISSIONER FOR PATENTS:

## A. Amendment Transmittal

Transmitted with this letter is

- (1) Amendment under 37 C.F.R. § 1.111; and
- (2) Return postcard.

The claim fee for the amended claims is as follows:

## COMPUTATION OF FEE FOR CLAIMS AS AMENDED

	Claims Remaining After Amendment		Highest Number Previously Paid For		Present Extra		Rate		Additional Fee
Total Claims	13	Minus	22	=	0	x	\$25/50	=	0.00
Independent Claims	3	Minus	3	=	0	x	\$100/200	=	0.00
Total additional Fee for this Amendment									\$0.00

B. Additional Fee Charges or Credit for Overpayment

The Commissioner is hereby authorized to charge any fees under 37 C.F.R. §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 501050. This authorization also hereby includes a request for any extensions of time of the appropriate length required upon the filing of any reply during the entire prosecution of this application. *A copy of this letter is enclosed.*

Direct all communications to:

**CUSTOMER NUMBER 128**

Respectfully submitted,

BLACK LOWE & GRAHAM<sup>PLLC</sup>

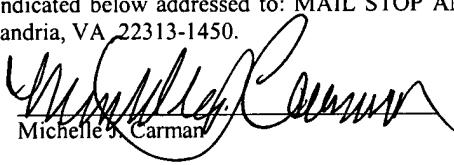


Michael S. Smith  
Registration No. 39,563  
Direct Dial: 206.749.9888

**MAIL CERTIFICATE**

I hereby certify that this communication is being deposited with the United States Postal Service via first class mail under 37 C.F.R. § 1.08 on the date indicated below addressed to: MAIL STOP AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

3/22/06  
Date of Deposit

  
Michelle J. Carman

MAIL STOP AMENDMENT



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Eskridge, Mark H.

Attorney Docket No. H0005288  
H000-1-1151

Serial No. 10/804,609

Group Art Unit: 2814

Filing Date: March 18, 2004

Examiner: NGUYEN, Dilinh

Title: FLIP CHIP BONDED MICRO-ELECTROMECHANICAL SYSTEM (MEMS)  
DEVICE

**RESPONSE TO RESTRICTION REQUIREMENT**

TO THE COMMISSIONER OF PATENTS: